

Variant: 001
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 TID #: TIDA-00650



TIDA-00650 REV E1 Bill of Materials

Item #	Designator	Quantity	Value	PartNumber	Manufacturer	Description	PackageReference
1	IPCB1	1		TIDA-00650	Any	Printed Circuit Board	
2	C1, C4, C8, C11	4	0.1uF	C1005X7R1H104K050BB	TDK	CAP, CERM, 0.1 µF, 50 V, +/- 10%, X7R, 0402	0402
3	C2, C3, C13, C15	4	1uF	GRM155R61A105KE15D	MuRata	CAP, CERM, 1 µF, 10 V, +/- 10%, X5R, 0402	0402
4	C5, C6	2	0.22uF	GRM155R60J224KE01D	MuRata	CAP, CERM, 0.22 µF, 6.3 V, +/- 10%, X5R, 0402	0402
5	C7, C12	2	0.27uF	GRM155R60J274KE01D	MuRata	CAP, CERM, 0.27 µF, 6.3 V, +/- 10%, X5R, 0402	0402
6	C9	1	1uF	UMK107AB7105KA-T	Taiyo Yuden	CAP, CERM, 1 µF, 50 V, +/- 10%, X7R, 0603	0603
7	C10	1	4.7uF	C1005X5R1A475K050BC	TDK	CAP, CERM, 4.7 µF, 10 V, +/- 10%, X5R, 0402	0402
8	C14	1	10uF	GRM155R61A106ME11	MuRata	CAP, CERM, 10 µF, 10 V, +/- 20%, X5R, 0402	0402
9	D1, D2, D5, D6	4	13V	PTVS13VP1UP_115	NXP Semiconductor	Diode, TVS, Uni, 13 V, 600 W, SOD-128	SOD-128
10	D3, D4	2	70V	BAV199-TP	Micro Commercial Components	Diode, Switching, 70 V, 0.215 A, SOT-23	SOT-23
11	D8	1	Green	LG L29K-G2J1-24-Z	OSRAM	LED, Green, SMD	1.7x0.65x0.8mm
12	H1	1		PCC-SMP-CLIP	Omega	Mounting bracket for PCC-SMP	
13	J1	1		PCC-SMP-K-5-R	Omega	Circuit Board Thermocouple Connector, Miniature Size, Type K, Horizontal installation, TH	20.8x6.3x15.5 mm
14	J2	1		LSS-110-01-F-DV-A	Samtec	Terminal/Socket Combo, 25mil, 10x2, Gold, SMT	Terminal Socket, 10x2, Gold, SMT
15	L1	1	5 ohm	BLM18BB050SN1D	MuRata	Ferrite Bead, 5 ohm @ 100 MHz, 0.7 A, 0603	0603
16	R1	1	10.0	CRCW040210R0FKED	Vishay-Dale	RES, 10.0, 1%, 0.063 W, 0402	0402
17	R2, R11	2	2.00Meg	CRCW04022M00FKED	Vishay-Dale	RES, 2.00 M, 1%, 0.063 W, 0402	0402
18	R4, R7, R8	3	47	CRCW040247R0JNED	Vishay-Dale	RES, 47, 5%, 0.063 W, 0402	0402
19	R5, R6, R9, R10	4	499	CRCW0402499RFKED	Vishay-Dale	RES, 499, 1%, 0.063 W, 0402	0402
20	R12	1	3.24k	PFC-W1206R-12-3241-B	TT Electronics/IRC	RES, 3.24 k, 0.1%, 0.333 W, 1206	1206
21	R13	1	240k	CRCW0402240KFKED	Vishay-Dale	RES, 240 k, 1%, 0.063 W, 0402	0402
22	R14	1	470	ERJ-2RKF4700X	Panasonic	RES, 470, 1%, 0.1 W, 0402	0402
23	R15	1	2.2Meg	CRCW04022M20JNED	Vishay-Dale	RES, 2.2 M, 5%, 0.063 W, 0402	0402
24	RT1	1	100 Ohm	32209210	Heraeus Sensor Technology	Temperature Sensor, 100ohm, TC=+3850ppm, TO-92, TH	TO-92, 2pin
25	U1	1		ADS1220IRVAR	Texas Instruments	Low-Power, Low-Noise, 24-Bit Analog-to-Digital Converter for Small Signal Sensors, RVA0016A	RVA0016A
26	U2	1		TS5A3159DBVR	Texas Instruments	1-? SPDT Analog Switch, DBV0006A	DBV0006A
27	D7	0	3.813V	PTZTE253.6B	Rohm	Diode, Zener, 3.813 V, 1 W, SMA	SMA
28	FID1, FID2, FID3	0		N/A	N/A	Fiducial mark. There is nothing to buy or mount.	N/A
29	LBL1	0		THT-14-423-10	Brady	Thermal Transfer Printable Labels, 0.650" W x 0.200" H - 10,000 per roll	PCB Label 0.650"H x 0.200"W
30	R3	0	2.00Meg	CRCW04022M00FKED	Vishay-Dale	RES, 2.00 M, 1%, 0.063 W, 0402	0402

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